

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YU BAO	08/09/2016
XIAOQIANG ZHOU	08/09/2016
JUN ZHOU	08/09/2016
BIN ZHONG	08/09/2016
HAIFENG ZHOU	08/09/2016
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<b>State/Country:</b>	CHINA
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15235208
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<b>Fax Number:</b>	
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<b>SIGNATURE:</b>	/Yifan Yin/
<b>DATE SIGNED:</b>	12/22/2016
<b>Total Attachments: 2</b>	
source=TC16060143US-#40077;#23431;#31614;#23383;#page1.tif	
source=TC16060143US-#40077;#23431;#31614;#23383;#page2.tif	

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

**METHOD OF REMOVING DUMMY GATE DIELECTRIC LAYER**

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on \_\_\_\_\_ (Application No. \_\_\_\_\_); and

WHEREAS, SHANGHAI Huali Microelectronics Corporation, a corporation of P.R. China whose post office address is No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China 201210 (hereinafter referred to as Assignees), and are desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignees is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignees, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No. \_\_\_\_\_, filed \_\_\_\_\_ (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignees, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with Assignees, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignees, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignees, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignees, its successors and assigns.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hands.

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Date: 2016.8.9

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